These preforms are designed specifically for SMP & SMPM series connectors. They provide optimum flow and fillet when used with the recommended preform well and are available in the following solders: Sn63, Sn96 or Sb5 for RACPO & RACMPO series and 80/20 Au/Sn for the RKCPO series.

NOTES: (1) Insert last 2 digits of desired solder in place of xx (63, 96 or b5).
(2) Tolerance on all dimensions is ±002
(3) 80/20 solder only available on RKCPO series
(4) Available in 80/20 Au/Sn solder only
(5) Two preforms required for flush mount. Contact SHP for recommendation for other mount styles.

<table>
<thead>
<tr>
<th>CONNECTOR SERIES</th>
<th>PREFORM PART NO.</th>
<th>ID</th>
<th>OD</th>
<th>t</th>
</tr>
</thead>
<tbody>
<tr>
<td>RACPO</td>
<td>SPPF-RACxx(1)(3)(5)</td>
<td>.171</td>
<td>.228</td>
<td>.027</td>
</tr>
<tr>
<td>RACMPO</td>
<td>SPPF-RACMxx(1)(3)</td>
<td>.133</td>
<td>.174</td>
<td>.039</td>
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<tr>
<td>RKCPO</td>
<td>SPPF-RKC8020(4)</td>
<td>.168</td>
<td>.108</td>
<td>.005</td>
</tr>
</tbody>
</table>

Example Part No. SPPF-RAC63

Solder Melting Temperatures

- Sn63: 183°C (361°F)
- Sn96: 221°C (430°F)
- Sb5: 232-240°C (450-464°F)
- 80/20: 280°C (536°F)

All dimensions are inches.